

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

MS2878

产品手册

产品简介

MS2878 是一款全桥 DMOS 有刷电机驱动芯片，最大工作范围 可达 $\pm 3.5A$ 和 40V 输入电压，用 PWM 来控制马达驱动的速度和 方向。如果将两个输入均置为低电平，则电机驱动器将进入低功耗 休眠模式。

MS2878 集成电流限制功能，该功能基于模拟输入 VREF 以 及 ISEN 引脚的电压。该器件能够将电流限制在某一已知水平，这 可显著降低系统功耗要求，并且无需大容量电容来维持稳定电 压，尤其是在电机启动和停转时。

内部关断功能包含过流保护、短路保护、欠压锁定和过温保护。

MS2878 提供一种带有裸露焊盘的 SOP-8 封装， 能有效改善 散热性能，且是无铅产品，引脚框采用 100%无锡电镀。

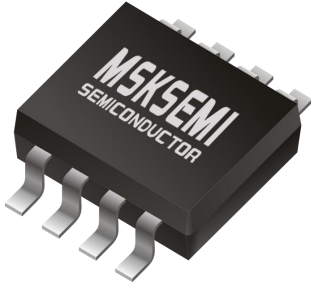
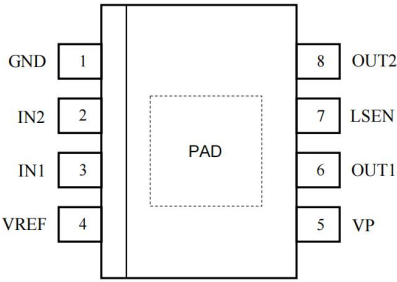
产品特点

- 宽电压供电， 6.5V-40V
- RDS (ON) 电阻为 600m Ω
- 3.5A 峰值驱动输出， 2A 持续输出能力
- 支持欠压锁定保护
- 低功耗休眠模式
- PWM 电流整流/限流/调向
- 支持短路保护
- 支持过温关断电路
- 自动故障恢复

产品用途

- 打印机及办公自动化设备
- 电器
- 机器人
- 工业设备

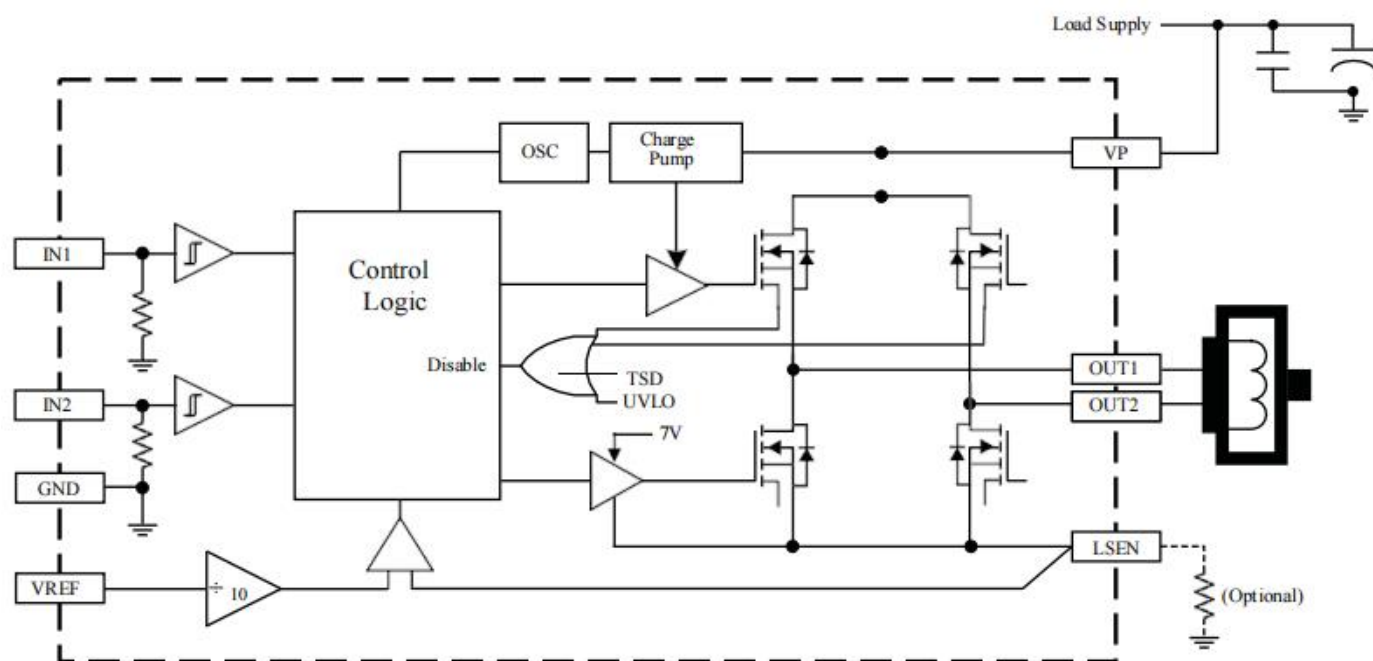
参考信息

ESOP-8	管脚定义	丝印
		

管脚定义

Number	Name	Function
1	GND	地
2	IN2	逻辑输入 2
3	IN1	逻辑输入 1
4	VREF	模拟输入
5	VP	功率电源
6	OUT1	DMOS 全桥输出 1
7	LSEN	检测电阻连接
8	OUT2	DMOS 全桥输出 2
—	PAD	散热 pad

功能框图



极限参数

Characteristic	Symbol	Notes	Rating	Unit
功率电源	VP		40	V
逻辑输入	V_{IN}		-0.3 ~ 6	V
V_{LSEN} 输入范围	V_{LSEN}		-0.3 ~ 6	V
Sense Voltage (LSEN pin)	V_{LSEN}		-0.5 ~ 0.5	V
输出电流	I_{OUT}	Duty cycle = 100%	3.5	A
工作温度	T_A	Temperature Range E	-40 ~ 85	°C
最大结温	$T_J(max)$		150	°C
储藏温度	T_{stg}		-55 ~ 150	°C

电特性参数

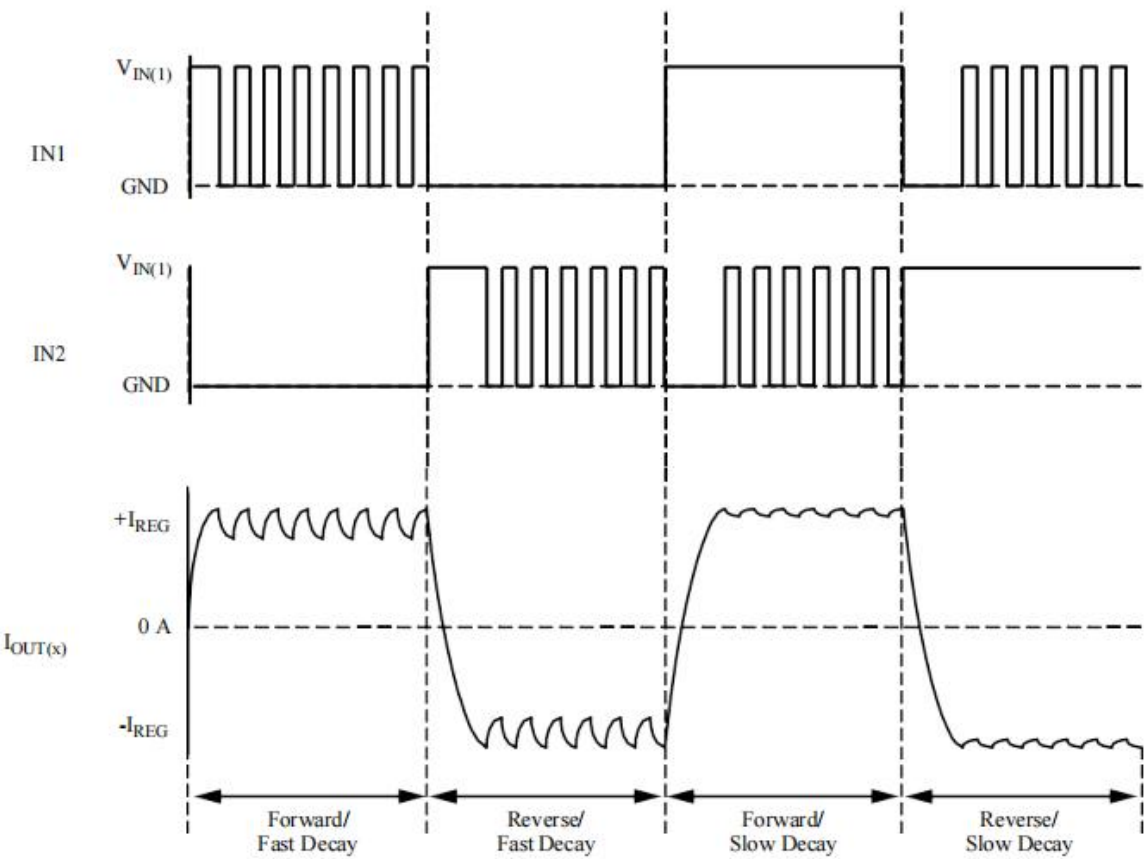
Characteristic	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
General						
Load Supply Voltage Range	V _P		6.5	—	40	V
R _{DS(on)} Sink + Source Total	R _{DS(on)}	I _{OUT} = 1 A , T _J = 25°C	—	0.6	0.8	Ω
		I _{OUT} = 1 A , T _J = 150°C	—	1	1.4	Ω
Load Supply Current	I _{VP}	f _{PWM} < 30 kHz	—	5	20	mA
		Low Power Standby mode	—	—	10	μA
Body Diode Forward Voltage	V _f	Source diode, I _f = −2.5 A	—	—	1.5	V
		Sink diode, I _f = 2.5 A	—	—	1.5	V
Logic Inputs						
Logic Input Voltage Range	V _{IN(1)}		2.0	—	—	V
	V _{IN(0)}		—	—	0.8	V
	V _{IN(STANDBY)}	Low Power Standby mode	—	—	0.4	V
Logic Input Current	I _{IN(1)}	V _{IN} = 2.0 V	—	40	100	μA
	I _{IN(0)}	V _{IN} = 0.8 V	—	16	40	μA
Logic Input Pull-Down Resistance	R _{LOGIC(PD)}	V _{IN} = 0 V = IN1 = IN2	—	50	—	kΩ
Timing						
Crossover Delay	COD		50	—	500	ns
VREF Input Voltage Range	V _{REF}		0	—	5	V
Current Gain	A _V	V _{REF} / I _{SEN} , V _{REF} = 5 V	9.5	—	10.5	V/V
Blank Time	BLANK		2	3		μs
Constant Off-time	t _{off}		16	25	34	μs
Standby Timer	t _{st}	IN1 = IN2 < V _{IN(STANDBY)}	—	1	1.5	ms
Power-Up Delay	pu		—	—	30	μs
Protection Circuits						
UVLO Enable Threshold	V _{UVLO}	V _p increasing	7	7.4	7.8	V
UVLO Hysteresis	V _{UVLOhys}		—	300	—	mV
Thermal Shutdown Temperature	T _{JTSD}	Temperature increasing	—	160	—	°C
Thermal Shutdown Hysteresis	T _{TSDhys}	Recovery = T _{JTSD} − T _{TSDhys}	—	15		°C

模块功能描述

MS2878 是一款有刷直流电机驱动器，VP 单电源供电， 内置电荷泵。两个逻辑输入控制 H 桥驱动器，该驱动器由四个 N-MOS 组成，能够以高达 3.5A 的峰值电流双向控制电机。该芯片利用电流衰减预置最大输出电流，能够将电流限制在某一已知水平。如果将两个输入均置为低电平，则电机驱动器将进入低功耗休眠模式。内部关断功能包含过流 保护、短路保护、欠压锁定和过温保护。

Characteristic Performance

PWM Control Timing Diagram



PWM Control Truth Table

IN1	IN2	$10 \times V_S > V_{REF}$	OUT1	OUT2	Function
0	1	False	L	H	Reverse
1	0	False	H	L	Forward
0	1	True	H/L	L	Chop (mixed decay), reverse
1	0	True	L	H/L	Chop (mixed decay), forward
1	1	False	L	L	Brake (slow decay)
0	0	False	Z	Z	Coast, enters Low Power Standby mode after 1 ms

Note: Z indicates high impedance.

CurrentControl

通过固定频率的 PWM 电流整流器，流过电机驱动桥臂的电流是被限制的或者是被控制的。在 DC 电机应用中，电流控制功能用于限制开启电流和停转电流。

当一个 H 桥被使能，流过相应桥臂的电流以一个斜率上升，此斜率由直流电压 VP 和电机的电感特性决定。当电流达到设定的阈值，驱动器会关闭此电流，直到下一个 PWM 循环开始。注意，在电流被使能的那一刻，LSEN 管脚上的电压是被忽略的，经过一个固定时间后，电流检测电路才被使能。这个消隐时间一般固定在 2μs。这个消隐时间同时决定了在操作电流衰减时的最小PWM时间。

PWM 目标电流是由比较器比较连接在 LSEN 管脚上的电流检测电阻上的电压乘以一个 10 倍因子和一个参考电压决定。参考电压通过 VREF 输入。以下公式为 100%计算目标电流：

$$I_{\text{Trip}}(\text{A}) = \frac{V_{\text{REF}}(\text{V})}{A_V \times R_{\text{LSEN}}(\Omega)} = \frac{V_{\text{REF}}(\text{V})}{10 \times R_{\text{LSEN}}(\Omega)}$$

电流衰减时序

当电流达到 I_{Trip} ，H 桥的两个下管打开，维持一个 t_{off} 时间(25μs)，然后相应上管再打开。

DEAD TIME

当输出由高电平转变成低电平，或者由低电平转变为高电平，死区时间的存在是为了防止上下管同时导通。死区时间内，输出是一个高阻态。当需要在输出上测量死区时间，需要根据相应管脚当时的电流方向来测量。如果电流是流出此管脚，此时输出端电压是低于地电平一个二极管压降；如果电流是流入此管脚，此时输出端电压是高于电源电压VP 一个二极管压降。

休眠模式

当IN1、IN2 都为低维持 1ms 以上，器件将进入休眠模式，从而大大降低器件空闲的功耗。进入休眠模式后，器件的H 桥被禁止，电荷泵电路停止工作。在 VP 上电时候，如果 IN1、IN2 都为低，芯片是立马进去休眠模式。当 IN1 或 IN2 翻转为高电平且至少维持 5μs，经过延迟约 50μs，芯片恢复到正常的操作状。

保护电路

MS2878 有过流保护，过温保护和欠压保护。

过流保护

芯片内置电流监测以保护芯片不被烧坏。如果输出短路到 VP 或 GND，芯片会输出高阻态并关断输出。这种锁存状态只能通过芯片重新上电来消除。在过流保护过程中，允许芯片超出最大工作条件一段时间后会触发锁存。

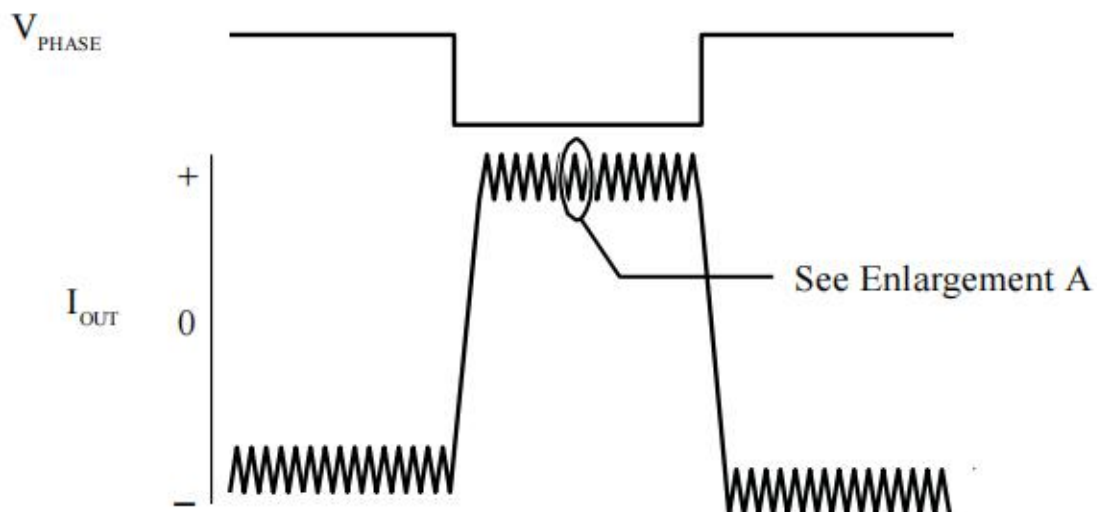
过温保护 (TSD)

如果结温超过安全限制阈值，H 桥的 FET 被禁止。一旦结温降到一个安全水平，所有操作会自动恢复正常。

欠压锁定保护(UVLO)

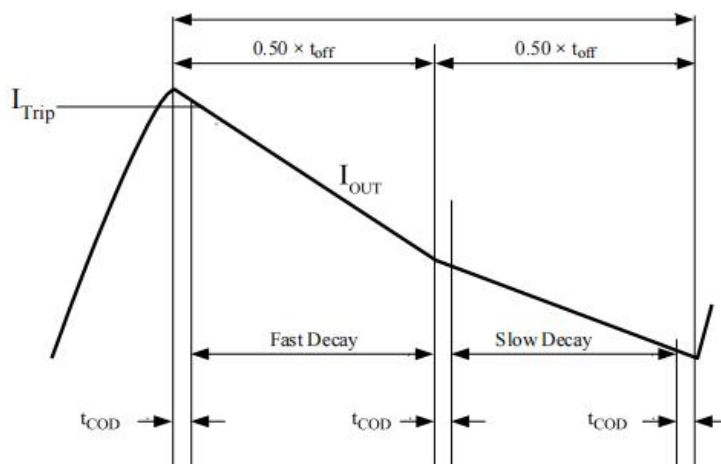
在任何时候，如果 VP 管脚上的电压降低到低于欠压锁定阈值，内部所有电路会被禁止，内部所有复位。当 VP 上的电压上升到 UVLO 以上，所有功能自动恢复。

Mixed Decay 运行模式

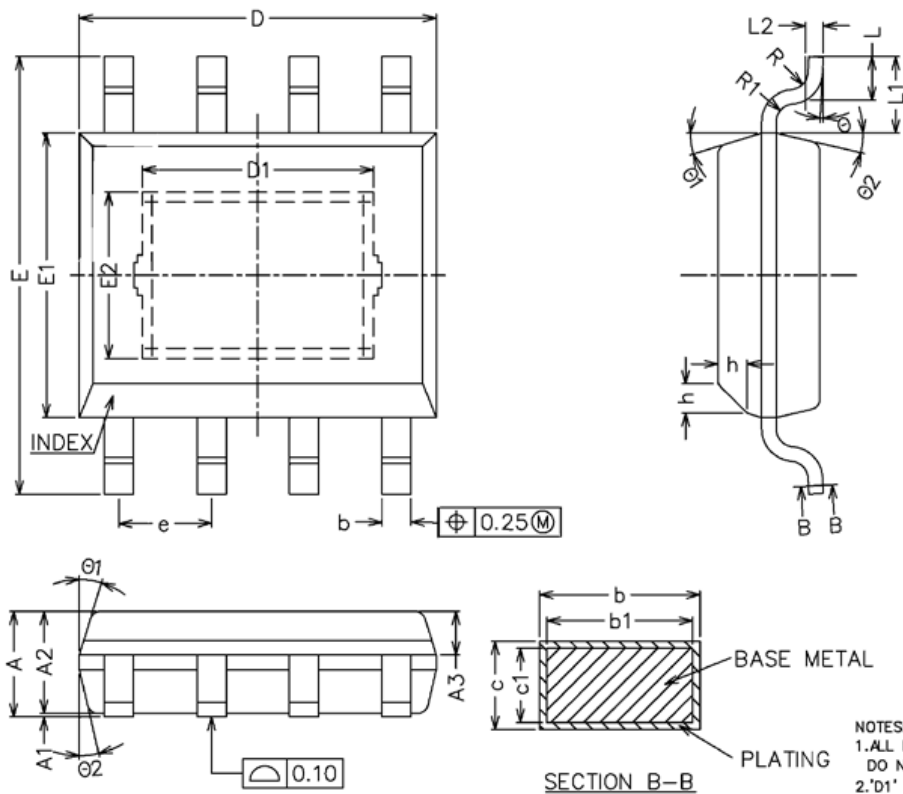


Enlargement A

Fixed Off-Time, $t_{\text{off}} = 25 \mu\text{s}$



封装信息



COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)			
SYMBOL	MIN	NOM	MAX
A	1.35	1.45	1.65
A1	0	—	0.15
A2	1.35	1.40	1.50
A3	0.50	0.60	0.70
b	0.38	—	0.47
b1	0.37	0.40	0.43
c	0.17	—	0.25
c1	0.17	0.20	0.23
D	4.80	4.90	5.00
D1	3.02	3.17	3.32
	1.98	2.13	2.28
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
E2	2.13	2.28	2.43
	1.98	2.13	2.28
e	1.17	1.27	1.37
L	0.45	0.60	0.80
L1	1.04REF		
L2	0.25BSC		
R	0.07	—	—
R1	0.07	—	—
h	0.30	0.40	0.50
θ	0°	—	8°
$\theta 1$	15°	17°	19°
$\theta 2$	11°	13°	15°

NOTES:
1.ALL DIMENSIONS REFER TO JEDEC STANDARD MS-012 AA
DO NOT INCLUDE MOLD FLASH OR PROTRUSION.
2.'D1' AND 'E2' ARE VARIABLES DEPENDING ON DIE PAD SIZES.

订购信息

P/N	PKG	QTY
MS2878	SOP-8	4000

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